



Product End-of-Life Disassembly Instructions

Product Category: Workstation
Marketing Name / Model [List multiple models if applicable.]
HP Z2 SFF G9 Workstation Desktop PC/FCW-F002SF-550&FCW-F002SF-450&FCW-F002SF-260

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact [HP's Sustainability Contact](#).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	<input checked="" type="checkbox"/> Main board (MB) PCB*1 <input checked="" type="checkbox"/> Solid state drive (SSD) PCB*1 <input checked="" type="checkbox"/> Graphic card PCB*1 <input type="checkbox"/> Wireless WAN module (WWAN) PCB <input type="checkbox"/> Touch module PCB <input checked="" type="checkbox"/> Power supply PCB*2 <input checked="" type="checkbox"/> External Keyboard (KB)*1 <input checked="" type="checkbox"/> External Mouse*1 <input checked="" type="checkbox"/> Memory PCB*2	9
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	<input checked="" type="checkbox"/> RTC/CMOS battery <input type="checkbox"/> Others: _____	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: <ul style="list-style-type: none"> <input type="checkbox"/> screws <input type="checkbox"/> snaps <input type="checkbox"/> adhesive <input type="checkbox"/> other. Explain _____ 	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches,		0

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
batteries		
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	<input type="checkbox"/> Panel LCD	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	<input checked="" type="checkbox"/> Power Supply capacitor(s) or condenser(s)	
External electrical cables and cords	<input checked="" type="checkbox"/> AC power cord <input type="checkbox"/> Audio, video or data cables <input type="checkbox"/> Other: _____	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	Philip #0
Screwdriver	Torx T8
Heatgun	N/A
Suction cup	N/A

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

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Template Revision D

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last updated May-2022

HPI instructions for this template are available at [EL-MF877-01](#)

1. Open and removed the access panel.
2. Removed the front bezel.
3. Disconnect the ODD SATA/Power cable from ODD.
4. Removed the ODD.
5. Flip the driver cage to the left
6. Disconnect the SATA cable from Motherboard.
7. Remove memory from Motherboard.
8. Open the PCI latch.
9. Press the button and remove the graphic card from Motherboard.
10. Figure 10 Press the button and Remove the graphic card from motherboard, See below is Graphic card PCB > 10 sq cm.
11. Disconnect the cable and remove the fan duct from cooler
12. Use T-15 screwdriver to loose the screws and remove the fan
13. Use T-15 screwdriver to loose the screws and remove cooler
14. Use T-15 screwdriver to loose the screws and separate the fan from cooler
15. Rotate the handle and open it up.
16. Remove the CPU from motherboard..
17. Remove the SSD from motherboard.
18. Disconnect all other cables from Motherboard.
19. Use T-15 screwdriver remove the screws on the PSU Chassis.
20. Press the PSU's latch on chassis and remove the PSU from chassis
21. Remove the battery from Motherboard.
22. Press the button and remove the heat sink.
23. Remove speaker from Chassis.
24. Use T-15 screwdriver to loose the screws from motherboard.
25. Remove Motherboard from chassis.
26. Remove the PCI slot covers (x5) from chassis.
27. Cut the cable tie
28. Remove screw for top
29. Remove FAN and inlet screw
30. Remove FG screw
31. Disconnect fan connector.
32. Remove PCB screw.
33. Cut output cable, AC inlet wire, LED wire.
34. Remove capacitors use solder iron.
35. Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it. (C103、 C305、 C306、 C307、 C309)

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: [End-of-Life Product Disassembly Instructions \(hp.com\)](http://hp.com)

Figure1 Open and removed the access panel.

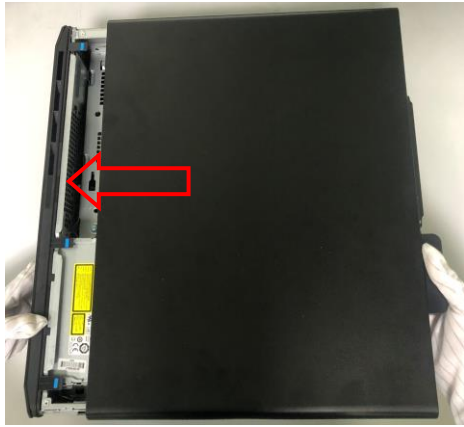


Figure2. Remove the front bezel



Figure3 Disconnect the ODD SATA/ Power cable from ODD



Figure4 Removed the ODD.



Figure5 Flip driver cage to the left

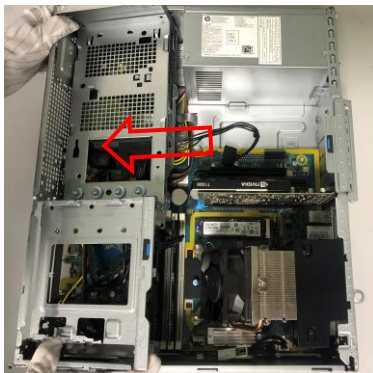
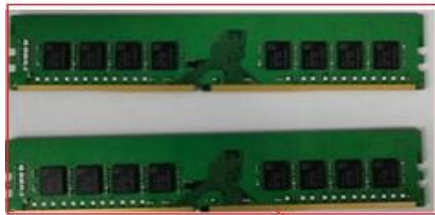
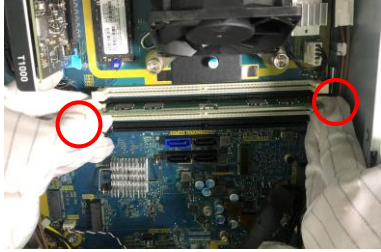


Figure6 Disconnect the SATA cable from Motherboard.



Figure7 Remove memory from Motherboard. See below Memory PCB area >10 sq cm.



Memory PCB

Figure8 Open the PCI latch.

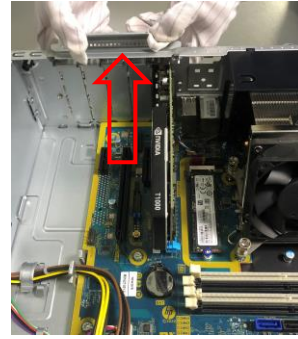


Figure9 Press the button and remove the graphic card from Motherboard.

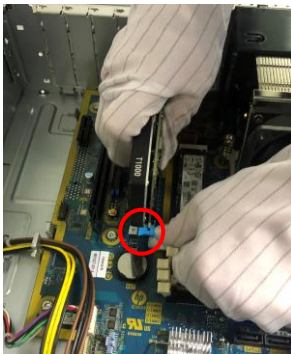


Figure10 Press the button and remove the graphic card from motherboard, See below is Graphic card PCB area >10 sq cm



Figure11 Disconnect the cable and remove the fan duct from cooler



Figure12 Use Philip #0 screwdriver to loose the screws and remove the fan



Figure13 Use Philip #0 screwdriver to loose the screws and remove cooler



Figure14 Use Philip #0 screwdriver to loose the screws and separate the fan from cooler



Figure15 Rotate the handle and open it up

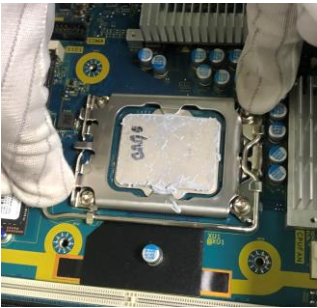


Figure16 Remove the CPU from Motherboard.



Figure17 Remove the SSD from motherboard. See below SSD PCB area >10 sq cm

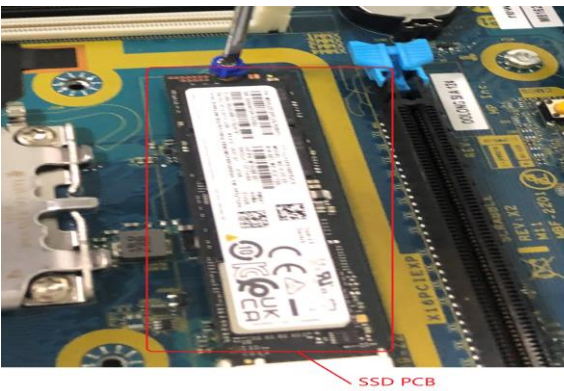


Figure18 Disconnect all other cables from Motherboard.

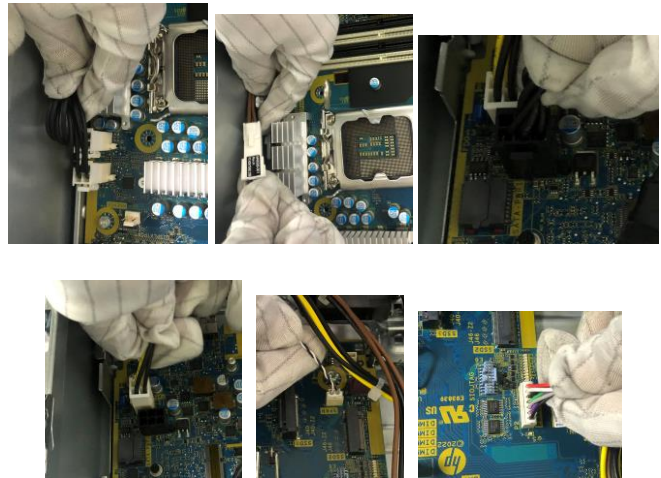


Figure19 Use Philip #0 screwdriver remove the screws on the PSU Chassis

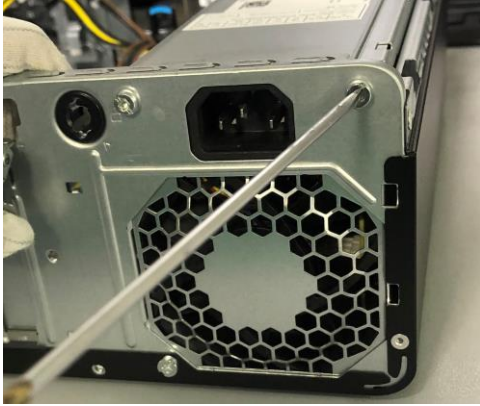


Figure20 Press the PSU's latch on chassis and remove the PSU from chassis



Figure21 Remove the battery from Motherboard.

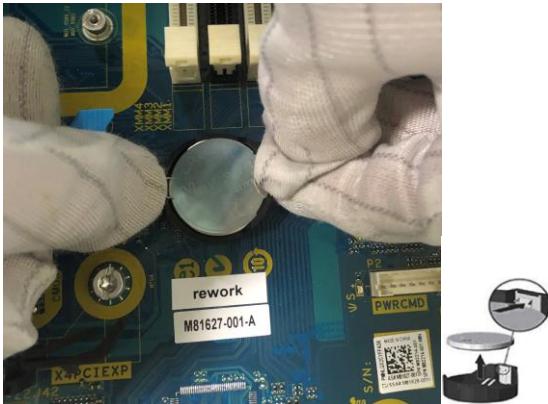


Figure22 Press the button and remove the heat sink



Figure23 Remove speaker from Chassis.



Figure24 Use Philip #0 screwdriver to loose the screws from motherboard.



Figure25 Remove the motherboard from chassis.



Figure26 Remove the PCI slot covers (x5) from chassis



Figure27 Cut the cable tie



Figure28 Remove screw for top.



Figure29 Remove FAN and inlet screw

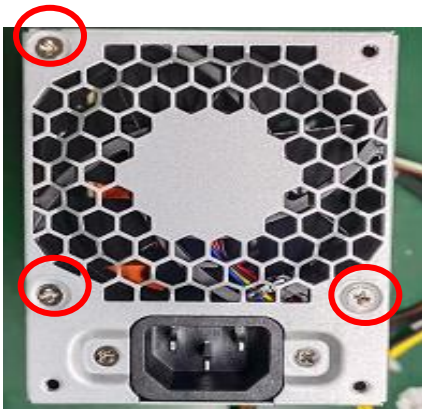


Figure30 Remove FG screw



Figure31 Disconnect fan connector



Figure32 Remove PCB screw.

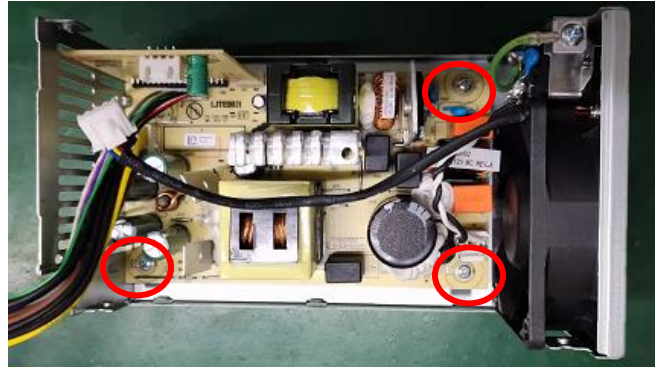


Figure33 Cut output cable, AC inlet wire, LED wire. There are tw PCA with a surface greater than 10 sq cm on PSU.



Figure34 Remove capacitors use solder iron.



Figure35 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it.(C103、 C305、 C306、 C307、 C309)

